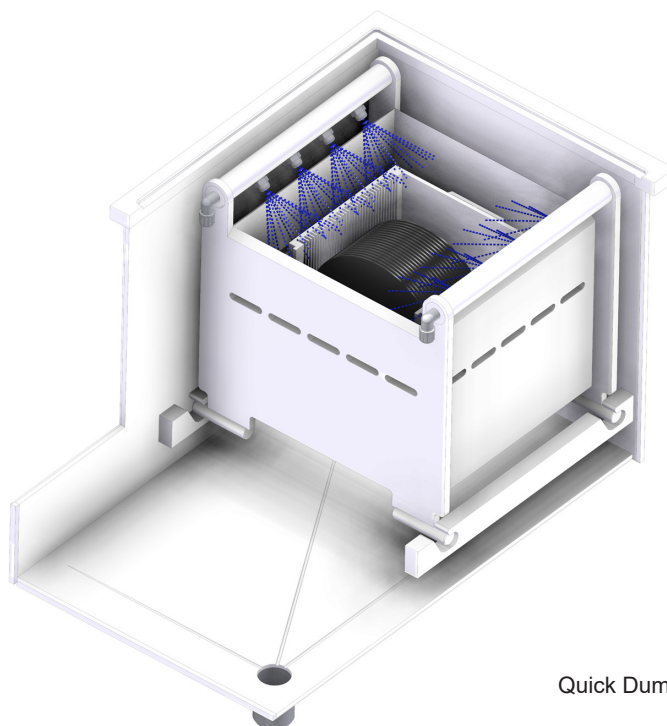


Quick Dump Rinse-Basin

for cleaning semiconductor wafers



Quick Dump Rinse (QDR)-Basin

Technical data

Material: State of the art plastic - polypropylene (PP)

Volume capacity: 22,5 Liter

Overflow: 360°

Number of spray nozzles: 8

Filling time: ca. 120 seconds

Dump time: ca. 10 seconds

Waferscarrier: 8"

Rinsing medium: DI-Water

QDR-Dump valve: 2,5 – 5,6 Kg / cm²

General information

Application:
Specially developed for the cleaning of semiconductor plates

Guaranteed personal protection:
Completed cleaning system

Modular construction:
Prozessbecken, Auffangbecken

Process bath:
Equipped with valve and spray system, can be removed from the system

Catch basin:
Holds the volume of the process tank, is permanently integrated in the system

Chemical resistance:
Economical plastic with broad chemical compatibility

Valve:
Bottom outlet valve (PP) with O-Rings (EPDM)

Spray system:
Two spray bars at the top of the process tank, each with 4 spray nozzles

Spray nozzles:
Full cone nozzles made of PP

